



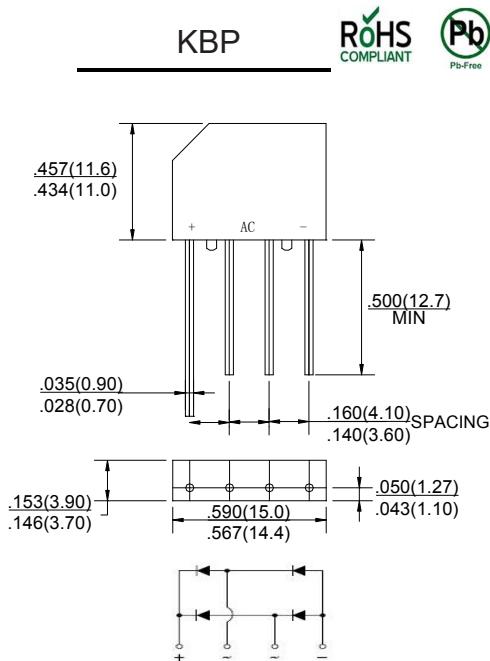
Single Phase 1.0Amp Glass Passivated Bridge Rectifier

Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- Ideal for printed circuit boards
- Low reverse leakage
- High forward surge current capability
- High temperature soldering guaranteed:
260°C/10 seconds, 0.375"(9.5mm) lead length,
5 lbs. (2.3kg) tension

Mechanical Data

- Case: Molded plastic body
- Terminals: Plated leads solderable per MIL-STD-750, Method 2026
- Polarity : Polarity symbols marked on case
- Mounting Position: Any
- Weight : 0.069 ounce, 1.95 grams



Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	Symbols	KBP1005	KBP101	KBP102	KBP104	KBP106	KBP108	KBP110	Units
Maximum repetitive peak reverse voltage	V _{RRM}	50	100	200	400	600	800	1000	VOLTS
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	VOLTS
Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	800	1000	VOLTS
Maximum average forward output rectified current at TA=50°C	I _(AV)					1.0			Amps
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}					35.0			Amps
Rating for Fusing(t<8.3ms)	I ² t				5.08				A ² s
Maximum instantaneous forward voltage at 1.0A	V _F				1.0				Volts
Maximum DC reverse current TA=25°C at rated DC blocking voltage TA=125°C	I _R				2	200			μA
Typical Junction Capacitance (Note 1)	C _J				20				pF
Typical Thermal Resistance (Note 2)	R _{QA}				28				°C/W
Operating junction temperature range	T _J				-55 to +150				°C
storage temperature range	T _{STG}				-55 to +150				°C

NOTES: 1. Measured at 1.0 MHz and applied reverse voltage of 4.0 Volts.

2. Unit mounted on P.C. board with 0.47" x 0.47"(12x12mm) copper pads, 0.375"(9.5mm) lead length.



Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

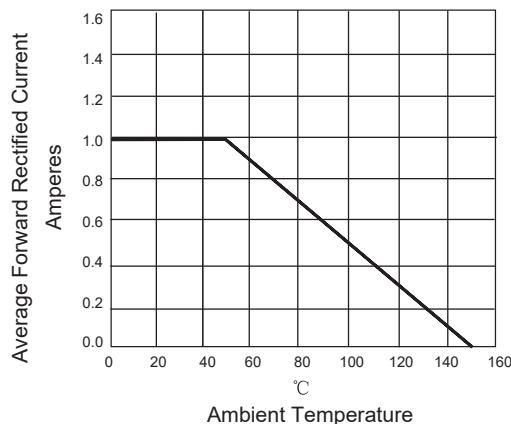


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PERLEG

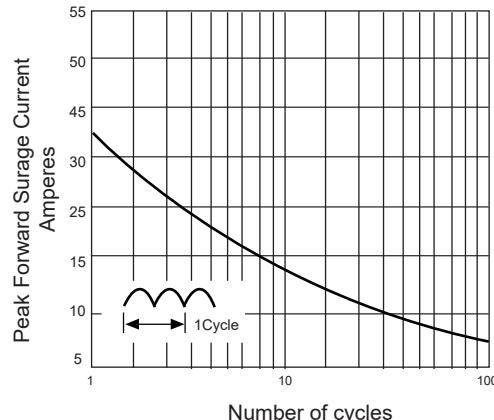


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

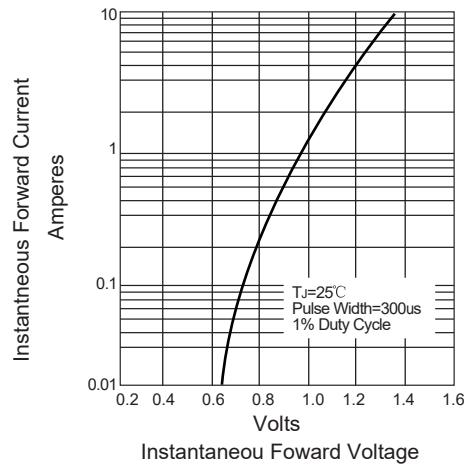


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS

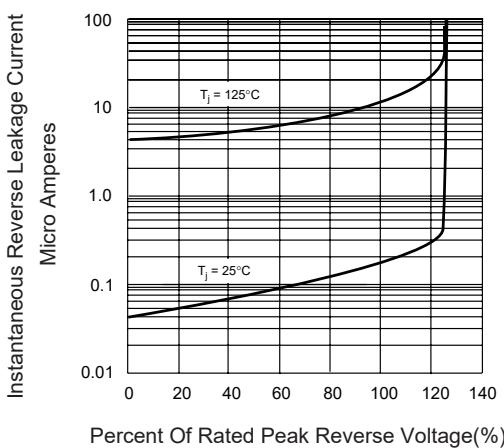
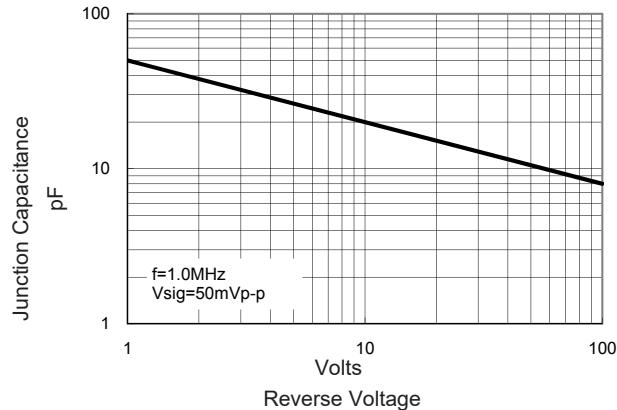
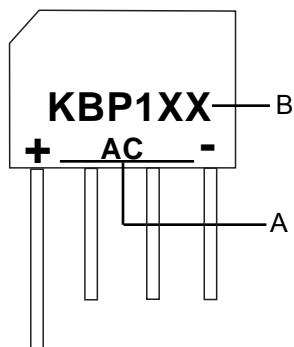


FIG. 5-TYPICAL JUNCTION CAPACITANCE



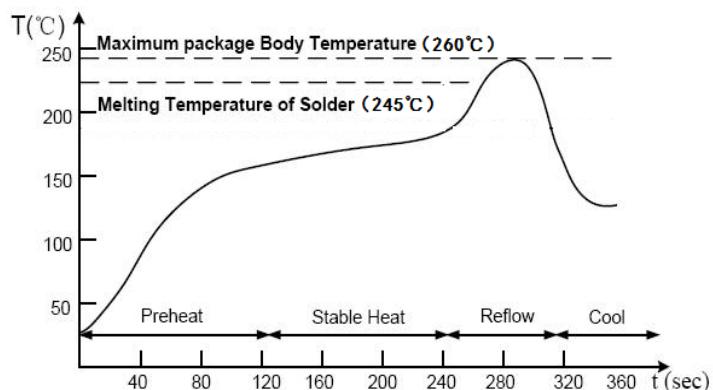


Marking



Symbol	Explanation
A	Polarity Symbol
B	Product Name, X: 005,01.....10

Suggested Soldering Temperature Profile



Note

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 260°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.